



### 80V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

## **Product Summary**

BV <sub>DSS</sub>	Rds(on) max	I <sub>D</sub> Tc = +25°C
80V	7.8mΩ @ V <sub>GS</sub> = 10V	91A
	11mΩ @ V <sub>GS</sub> = 4.5V	77A

# **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- DC-DC Converters
- Load Switch

### **Features**

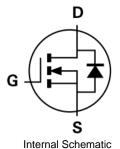
- Rated to +175°C Ideal for High Ambient Temperature **Environments**
- 100% Unclamped Inductive Switching (UIS) Test in Production -Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> Minimizes On-State Losses
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH8008LPSQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

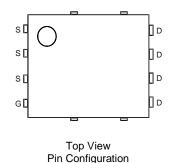
https://www.diodes.com/quality/product-definitions/

## **Mechanical Data**

- Case: PowerDI®5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3)
- Weight: 0.097 grams (Approximate)







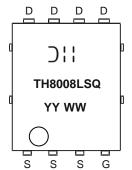
## Ordering Information (Note 4)

Part Number		Case	Packaging		
	DMTH8008LPSQ-13	PowerDI5060-8	2,500/Tape & Reel		
Notes:	Notes: 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant, All applicable RoHS exemptions applied.				

1, EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant, All applicable RoHS exemptions applied.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



) | | = Manufacturer's Marking TH8008LSQ = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 19 = 2019)WW = Week (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated.



# **Maximum Ratings** (@ $T_C = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	80	V		
Gate-Source Voltage	Vgss	±20	V		
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 7)	lo	91 64	А		
Maximum Continuous Body Diode Forward Current (Note	Is	69	Α		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			l <sub>DM</sub>	360	Α
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)			I <sub>SM</sub>	360	Α
Avalanche Current, L = 0.1mH (Note 8)			las	23	Α
Avalanche Energy, L = 0.1mH (Note 8)			Eas	26.5	mJ

# Thermal Characteristics ( $@T_C = +25^{\circ}C$ , unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	P <sub>D</sub>	1.6	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	93	°C/W
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	PD	3.4	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Reja	44	°C/W
Total Power Dissipation (Note 7)	Tc = +25°C	PD	100	W
Thermal Resistance, Junction to Case (Note 7)		R <sub>0</sub> JC	1.5	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

# Electrical Characteristics (@Tc = +25°C, unless otherwise specified.)

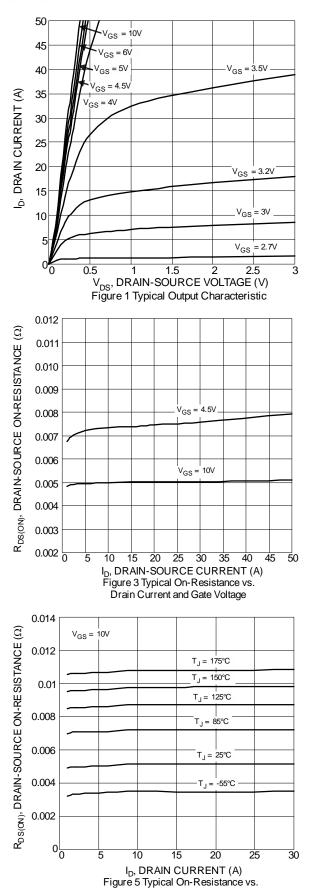
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)		I .					
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	80	_	_	V	$V_{GS} = 0V$ , $I_D = 1mA$	
Zero Gate Voltage Drain Current	IDSS	_	_	1	μΑ	V <sub>DS</sub> = 64V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	Igss	_	_	±100	nA	V <sub>G</sub> S = ±20V, V <sub>D</sub> S = 0V	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	Vgs(TH)	1.3	_	2.8	V	$V_{DS} = V_{GS}$ , $I_D = 1mA$	
Static Drain-Source On-Resistance	0	_	5	7.8	mΩ	Vgs = 10V, ID = 14A	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	8	11	11122	V <sub>G</sub> S = 4.5V, I <sub>D</sub> = 12A	
Diode Forward Voltage	VsD	_	8.0	1.2	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = 14A	
DYNAMIC CHARACTERISTICS (Note 10)	<u>.                                      </u>						
Input Capacitance	Ciss	_	2345	_		V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V, f = 1MHz	
Output Capacitance	Coss	_	842	_	pF		
Reverse Transfer Capacitance	Crss	_	51.9	_			
Gate Resistance	Rg	_	1.7	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_{\mathrm{G}}$	_	21.7	_			
Total Gate Charge (V <sub>GS</sub> = 10V)	Q <sub>G</sub>	_	41.2	_	nC	\/ 40\/ I- 20	
Gate-Source Charge	Qgs	_	5.0	_	IIC	$V_{DD} = 40V$ , $I_D = 2A$	
Gate-Drain Charge	$Q_{GD}$	_	10.6	_			
Turn-On Delay Time	t <sub>D</sub> (ON)	_	5.8	_			
Turn-On Rise Time	t <sub>R</sub>	_	5.4	_	20	$V_{DD} = 40V, V_{GS} = 10V,$	
Turn-Off Delay Time	t <sub>D</sub> (OFF)	_	24.5	_	ns	$I_D = 2A$ , $R_G = 1.6\Omega$	
Turn-Off Fall Time	tF	_	43.2	_			
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	61	_	ns	I= 2A di/dt 100A/vo	
Body Diode Reverse Recovery Charge	Qrr	_	181	_	nC	$I_F = 2A$ , di/dt = 100A/ $\mu$ s	

## Notes:

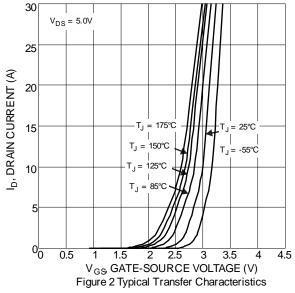
- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
  7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J = +25$ °C.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.

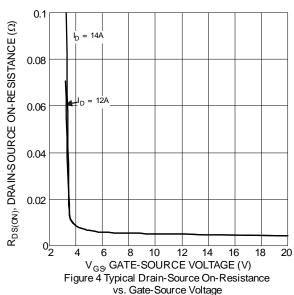


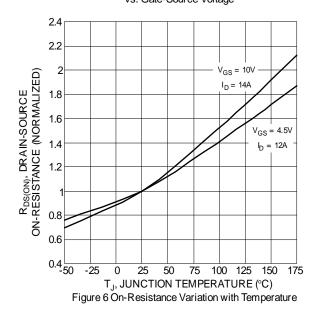




Drain Current and Temperature

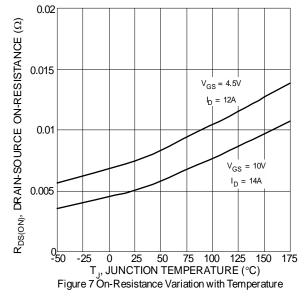


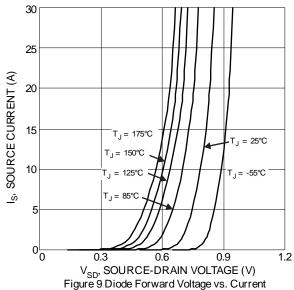


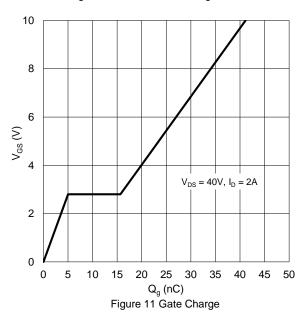












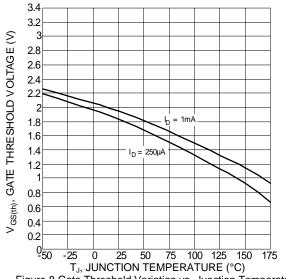
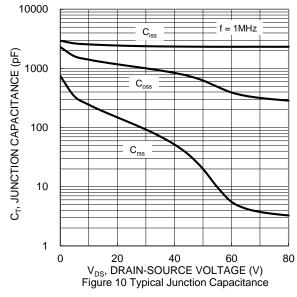
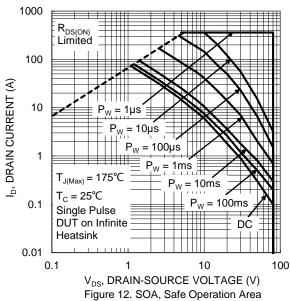
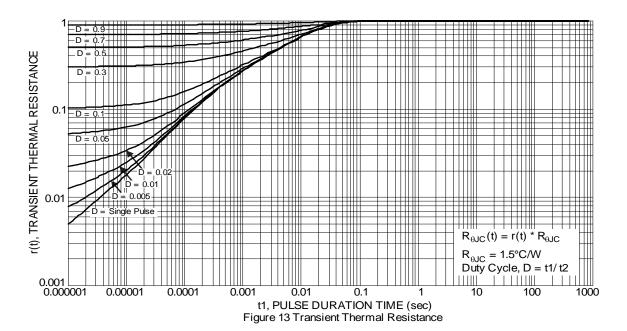


Figure 8 Gate Threshold Variation vs. Junction Temperature







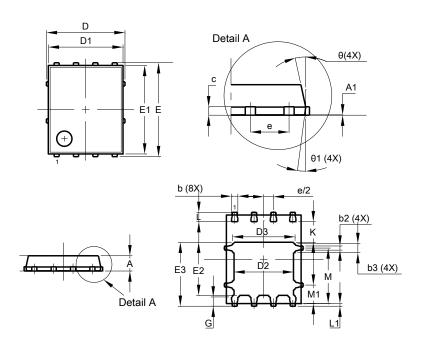




# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8

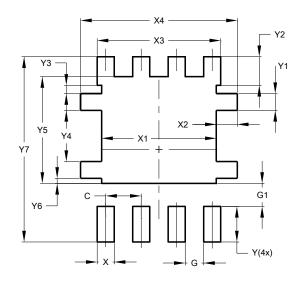


PowerDI5060-8				
Dim	Min	Тур		
Α	0.90	1.00		
A1	0.00	0.05	-	
b	0.33	0.51	0.41	
b2	0.200	0.350	0.273	
b3	0.40	0.80	0.60	
С	0.230	0.330	0.277	
D	,	5.15 BSC		
D1	4.70	5.10	4.90	
D2	3.70	4.10	3.90	
D3	3.90	4.30	4.10	
Е		6.15 BSC	;	
E1	5.60	6.00	5.80	
E2	3.28	3.68	3.48	
E3	3.99	4.39	4.19	
е	1.27 BSC			
G	0.51	0.71	0.61	
K	0.51	-	-	
L	0.51	0.71	0.61	
L1	0.100	0.200	0.175	
М	3.235	4.035	3.635	
M1	1.00	1.40	1.21	
Θ	10°	12°	11°	
Θ1	6°	8°	7°	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8



Dimensions	Value (in mm)			
С	1.270			
G	0.660			
G1	0.820			
X	0.610			
X1	4.100			
X2	0.755			
Х3	4.420			
X4	5.610			
Y	1.270			
Y1	0.600			
Y2	1.020			
Y3	0.295			
Y4	1.825			
Y5	3.810			
Y6	0.180			
Y7	6.610			



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